

## CMOS Hex 'D'-Type Flip-Flop

### High-Voltage Types (20-Volt Rating)

■ CD40174B consists of six identical 'D'-type flip-flops having independent DATA inputs. The CLOCK and CLEAR inputs are common to all six units. Data is transferred to the Q outputs on the positive-going transition of the clock pulse. All six flip-flops are simultaneously reset by a low level on the CLEAR input.

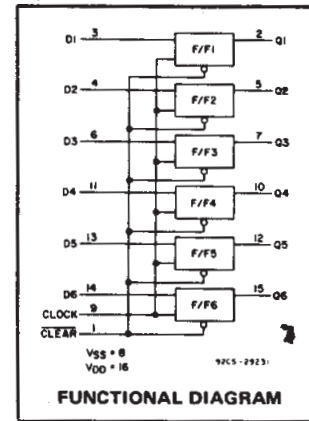
The CD40174B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V <sub>DD</sub> )	-0.5V to +20V
Voltages referenced to V <sub>SS</sub> Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	-0.5V to V <sub>DD</sub> + 0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (P <sub>D</sub> ):	
For T <sub>A</sub> = -55°C to +100°C	500mW
For T <sub>A</sub> = +100°C to +125°C	Derate Linearly at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )	-55°C to +125°C
STORAGE TEMPERATURE RANGE (T <sub>stg</sub> )	-65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	+265°C

### Features:

- 5-V, 10-V, and 15-V parametric rating
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range):  
1 V at V<sub>DD</sub> = 5 V  
2 V at V<sub>DD</sub> = 10 V  
2.5 V at V<sub>DD</sub> = 15 V
- Meets all requirements of JEDEC Tentative Standard No. 13A, "Standard Specifications for Description of 'B' Series CMOS Devices"



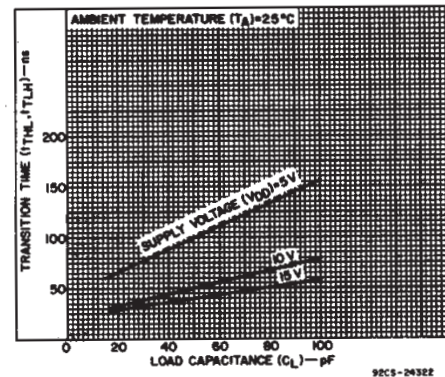
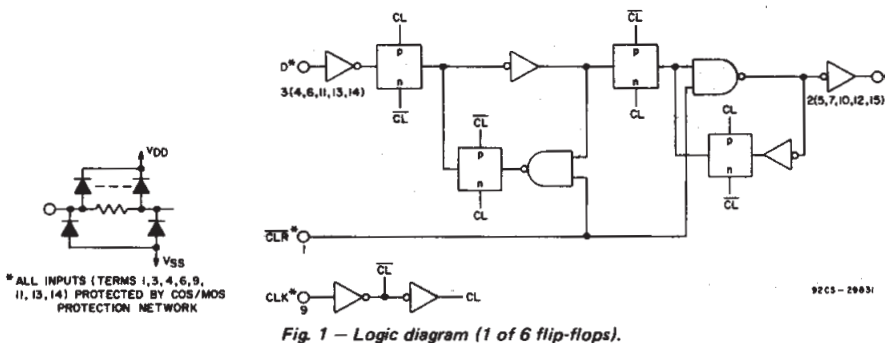
### Applications:

- Shift Registers
- Buffer/Storage Registers
- Pattern Generators

### TRUTH TABLE FOR 1 OF 6 FLIP-FLOPS

INPUTS		OUTPUT	
CLOCK	DATA	CLEAR	Q
0	0	1	0
0	1	1	1
1	X	1	NC
X	X	0	0

1 = High Level      X = Don't Care  
0 = Low Level      NC = No Change

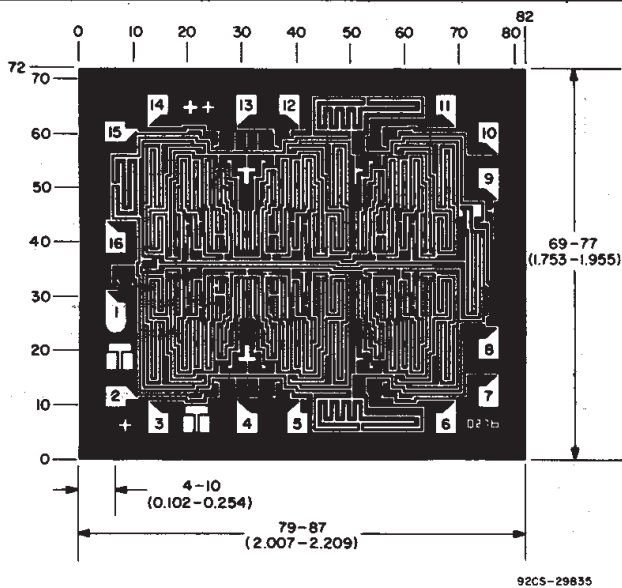


## CD40174B Types

**RECOMMENDED OPERATING CONDITIONS** at  $T_A = 25^\circ\text{C}$ , Except as Noted.

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	$V_{DD}$ (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For $T_A =$ Full Package-Temperature Range)	—	3	18	V
Data Setup Time, $t_{SU}$	5 10 15	40 20 10	— — —	ns
Data Hold Time, $t_H$	5 10 15	80 40 30	— — —	ns
Clock Input Frequency, $f_{CL}$	5 10 15	— dc —	3.5 6 8	MHz
Clock Input Rise or Fall Time, $t_{rCL}$ , $t_{fCL}$	5 10 15	— — —	15 15 15	$\mu\text{s}$
Clock Input Pulse Width, $t_{WL}$ , $t_{WH}$	5 10 15	130 60 40	— — —	ns
Clear Pulse Width, $t_{WL}$	5 10 15	100 50 40	— — —	ns
Clear Removal Time, $t_{REM}$	5 10 15	0 0 0	— — —	ns



Dimensions and pad layout for CD40174BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

The photographs and dimensions of each CMOS chip represent a chip when it is part of the wafer. When the wafer is separated into individual chips, the angle of cleavage may vary with respect to the chip face for different chips. The actual dimensions of the isolated chip, therefore, may differ slightly from the nominal dimensions shown. The user should consider a tolerance of  $-3$  mils to  $+16$  mils applicable to the nominal dimensions shown.

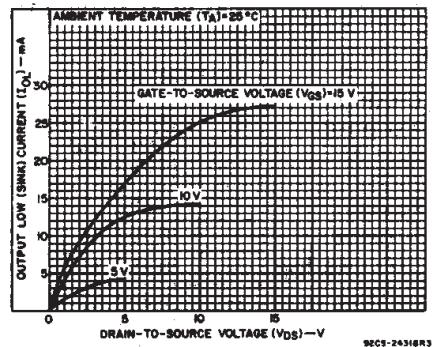


Fig. 3— Typical output low (sink) current characteristics.

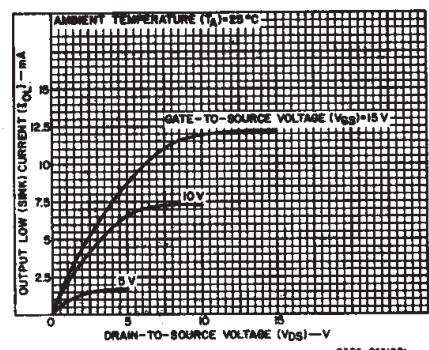


Fig. 4— Minimum output low (sink) current characteristics.

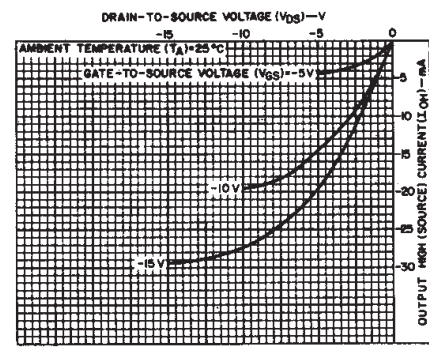


Fig. 5— Typical output high (source) current characteristics.

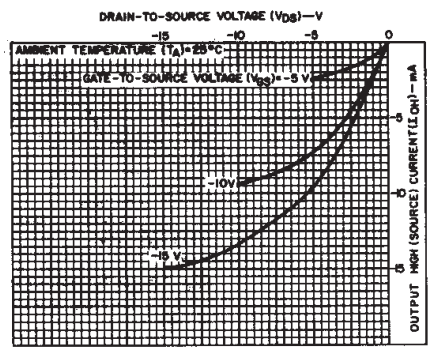


Fig. 6— Minimum output high (source) current characteristics.

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# CD40174B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	—	0.5	5	1	1	30	30	—	0.02	1	μA
	—	0.10	10	2	2	60	60	—	0.02	2	
	—	0.15	15	4	4	120	120	—	0.02	4	
	—	0.20	20	20	20	600	600	—	0.04	20	
Output Low (Sink) Current I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	—	0.5	5	0.05				—	0	0.05	V
	—	0.10	10	0.05				—	—	0.05	
	—	0.15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V <sub>OH</sub> Min.	—	0.5	5	4.95				4.95	5	—	V
	—	0.10	10	9.95				9.95	10	—	
	—	0.15	15	14.95				14.95	15	—	
Input Low Voltage, V <sub>IL</sub> Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1.9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, V <sub>IH</sub> Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1.9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current I <sub>IN</sub> Max.	—	0.18	18	±0.1	±0.1	±1	±1	—	±10 <sup>-5</sup>	±0.1	μA

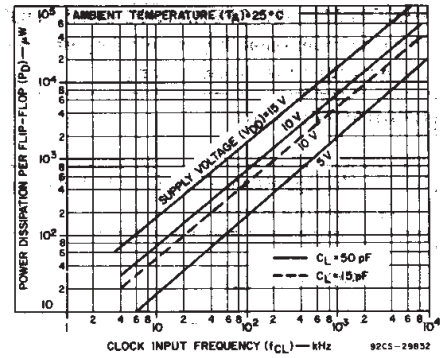


Fig. 7—Typical dynamic power dissipation as a function of CLOCK frequency.

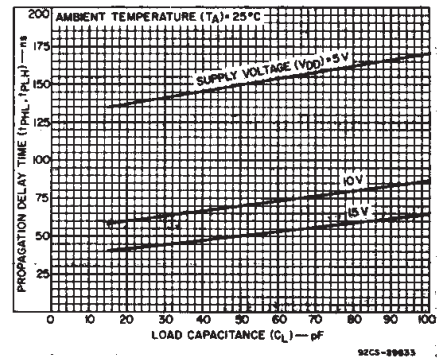


Fig. 8—Typical propagation delay time (CLOCK to OUTPUT) as a function of load capacitance.

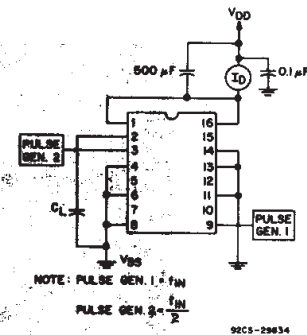


Fig. 9—Dynamic power dissipation test circuit.

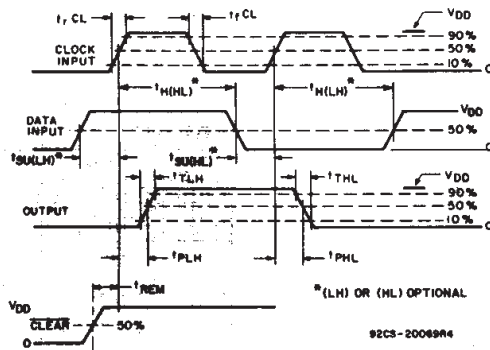


Fig. 10—Definition of setup, hold, propagation delay, and removal times.

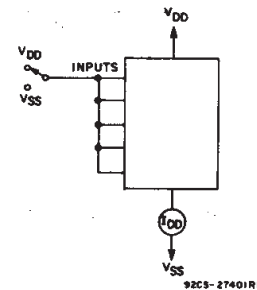


Fig. 11—Quiescent device current test circuit.

# CD40174B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^\circ\text{C}$ ;  
 Input  $t_r, t_f = 20\text{ ns}$ ,  $C_L = 50\text{ pF}$ ,  $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS $V_{DD}$ (V)	LIMITS			UNITS
		Min.	Typ.	Max.	
Propagation Delay Time Clock to Output, $t_{PHL}, t_{PLH}$	5	—	150	300	ns
	10	—	70	140	
	15	—	50	100	
Clear to Output, $t_{PHL}$	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Transition Time, $t_{THL}, t_{TLH}$	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Minimum Pulse Width, Clock, $t_{WL}, t_{WH}$	5	—	65	130	ns
	10	—	30	60	
	15	—	20	40	
Clear, $t_{WL}$	5	—	50	100	ns
	10	—	25	50	
	15	—	20	40	
Minimum Data Setup Time, $t_{SU}$	5	—	20	40	ns
	10	—	10	20	
	15	—	0	10	
Minimum Data Hold Time, $t_H$	5	—	40	80	ns
	10	—	20	40	
	15	—	15	30	
Maximum Clock Frequency, $f_{CL}$	5	3.5	7	—	MHz
	10	6	12	—	
	15	8	16	—	
Maximum Clock Rise or Fall Time, $t_{rCL}, t_{fCL}$	5	15	—	—	$\mu\text{s}$
	10	15	—	—	
	15	15	—	—	
Input Capacitance, $C_{IN}$	Clear	—	25	40	pF
	All other	—	5	7.5	
Minimum Clear Removal Time, $t_{REM}$	5	—	-40	0	ns
	10	—	-15	0	
	15	—	-10	0	

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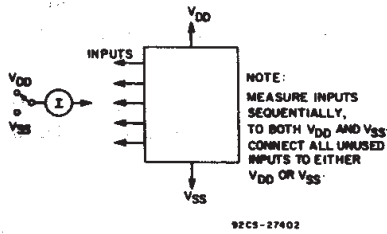


Fig. 12 - Input current test circuit.

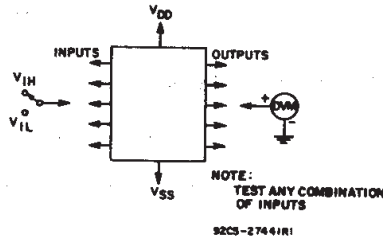
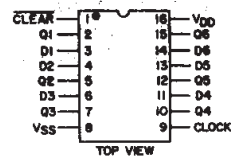


Fig. 13 - Input voltage test circuit.

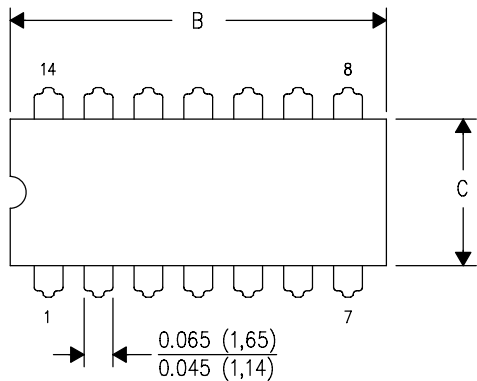
### TERMINAL ASSIGNMENT



# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

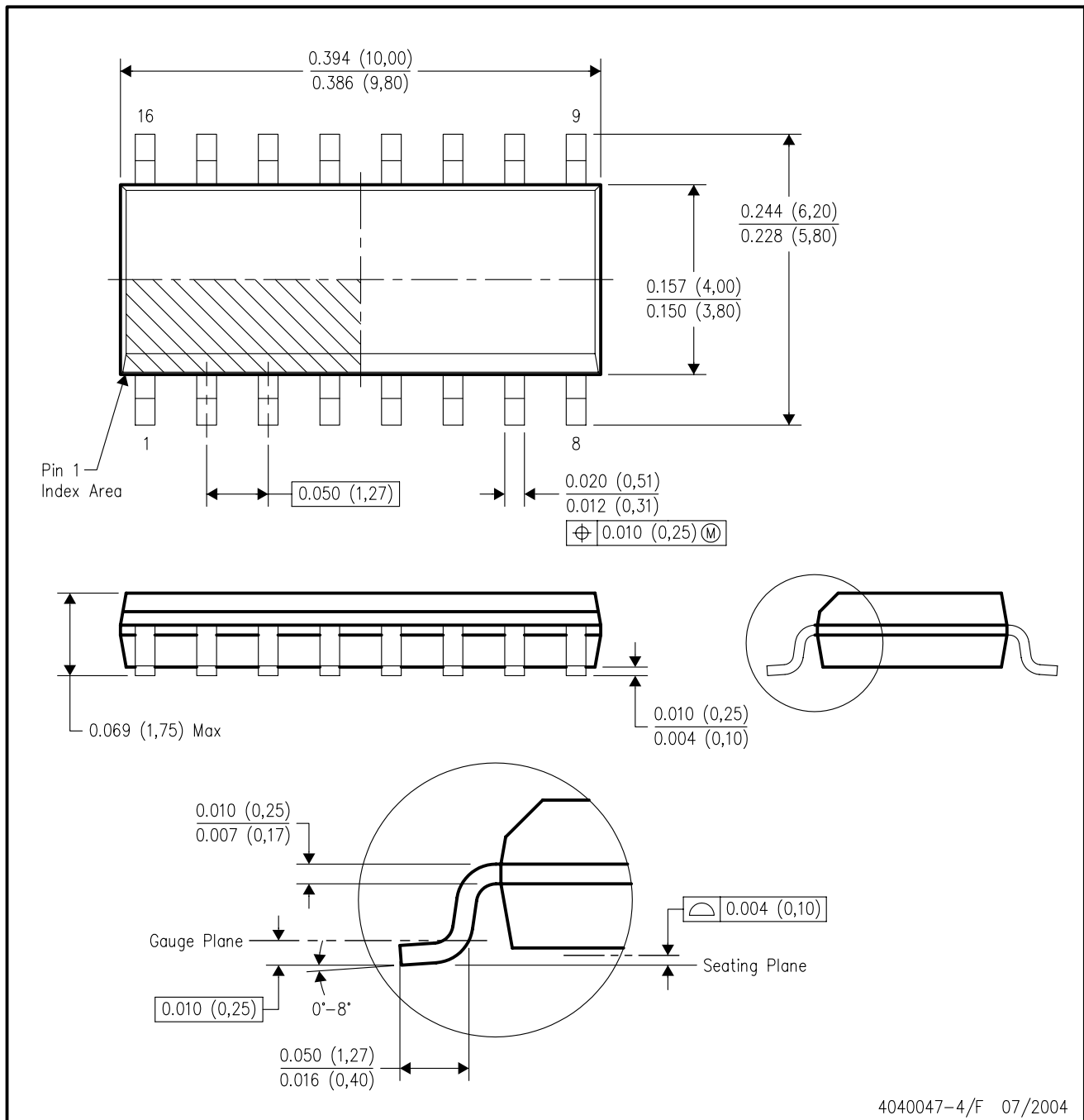
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/F 07/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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